



## Advance Product Change Notification

201512004A

**Issue Date:** 04-Jan-2016

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# QUALITY

### Management Summary

Assembly site transfer for the 20pin DIP packages of the 8 Bit Microcontroller Product Line from assembly site APB (NXP Semiconductors Assembly Plant Bangkok Thailand) to Amkor Philippines.

### Change Category

<input type="checkbox"/> Wafer Fab process	<input checked="" type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input checked="" type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

## Assembly Site Transfer for MCU 20pin DIP Packages (APB Thailand to Amkor Philippines)

### Details of this Planned Change

Transfer remaining production of 20pin DIP packages from APB (NXP Semiconductors Assembly Plant Bangkok Thailand) to subcontractor Amkor Philippines.

NXP will transfer all remaining production of 20pin DIP packages from in-house assembly APB (Bangkok) to the subcontractor Amkor Philippines.

There will be no changes to the test location. Wafer testing will be performed at APK and final test will be performed at APB.

Package assembly will be transferred from APB to Amkor with the following BOM changes:

1. Leadframe will be changed from NXP DIP20 PPF Leadframe to Amkor DIP20 CuFe2P leadframe with Ag spot plating. This is the standard Amkor leadframe and is being changed due to compatibility with Amkor tooling.
2. Die-attach will be changed from Henkel 71-1D to Henkel 8361J, which is standard die-attach material at Amkor Philippines.
3. Wire size will change from 20um to 25um.

4. Mold compound will change from EME-6210SR-L to Sumitomo G600, which is standard material at Amkor Philippines.
5. Lead finish will change from PPF to Matte Tin.
6. Tube will change from NXP DIP40 tube to Amkor Philippines DIP40 tube.

Please refer to the attached PDF file for all the Package Outline Drawing (POD) changes.

The POD changes include changes to the total package height, standoff height, package thickness, outer leadwidth, package length, tip to tip distance and package width.

The two critical POD differences are:

- 1) Package length 'D' is changing from min-max of 1.045in - 1.060in to a min-max of 1.025in to 1.035in.
- 2) Length from edge of package to pin 1, the 'Z' dimension on POD is not measured at Amkor.

#### **Why do we Plan this Change**

The 20pin DIP packages have been identified as End Of Life (EOL) products.

In order to support current production, NXP has decided to transfer the DIP assembly to NXP's subcontractor Amkor to have sufficient load to maintain these DIP assembly lines.

#### **Identification of Affected Products**

Top side marking

Only line 3, second letter, on assembly centre code will be changed from 'n' to 'u'

n - ABP Assembly

u - Amkor Assembly

(Old-TnGYWW, New-TuGYWW)

### **Product Availability**

#### **Sample Information**

Samples are available from 01-Mar-2016

#### **Production**

Planned first shipment 01-Jun-2016

### **Impact**

no impact to the product's functionality anticipated.

No impact on function, quality, reliability and manufacturability is anticipated.

#### **Data Sheet Revision**

No impact to existing datasheet

#### **Disposition of Old Products**

Existing inventory will be shipped until depleted

### **Additional information**

### **Timing and Logistics**

The Self Qualification Report will be ready on 01-Apr-2016.

The Final PCN is planned to be issued on: 01-Apr-2016.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 03-Feb-2016.

For information on shipping and logistics related issues please contact BL Operations Manager Swaminathan Ramesh at swaminathan.ramesh@nxp.com

### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Customer Focus, Passion to Win.

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